

60V P-Channel Enhancement Mode MOSFET

Description

The CP50P06G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- ◆ $V_{DS} = -60V$, $I_D = -50A$
 $R_{DS(ON)}(Typ.) = 27.5m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)}(Typ.) = 33.3m\Omega$ @ $V_{GS} = -4.5V$
- ◆ High density cell design for ultra low $R_{DS(ON)}$
- ◆ Fully characterized avalanche voltage and current
- ◆ Good stability and uniformity with high E_{AS}
- ◆ Excellent package for good heat dissipation

Application

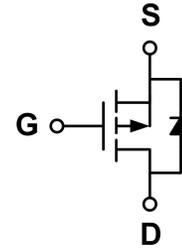
- ◆ Load switch

Package

- ◆ TO-252-2L

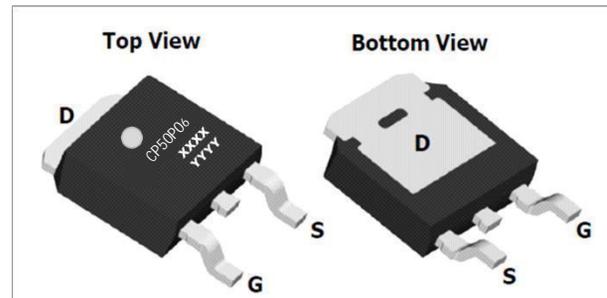


Schematic diagram



Marking and pin assignment

TO-252-2L



XXXX: Wafer Information YYYY:
Quality Code

Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
CP50P06G-G	-55°C to +150°C	TO-252-2L	2500

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit	
Drain-source voltage	V_{DS}	-60	V	
Gate-source voltage	V_{GS}	±20	V	
Continuous Drain Current	I_D	TC=25°C	-50	A
		TC=125°C	-25	
Pulsed Drain Current	I_{DP}	-200	A	
Avalanche Current	I_{AS}	-50	A	
Avalanche energy(L=1mH) ^(note1)	E_{AS}	600	mJ	
Maximum power dissipation	P_D	TC=25°C	85	W
		TC=100°C	44	
Operating junction Temperature range	T_j	-55—150	°C	

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-60	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-60V, V _{GS} =0V	-	-	-1	μA
		T _J =85°C	-	-	-30	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.0	-1.7	-2.5	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =-10V, I _D =-20A	-	27.5	33	mΩ
		V _{GS} =-4.5V, I _D =-20A	-	33.3	40	
Forward Transconductance	g _{FS}	V _{DS} =-10V, I _D =-20A	-	25	-	S
Diode Characteristics						
Diode Forward Voltage ¹	V _{SD}	I _{SD} =-1A, V _{GS} =0V	-	-0.72	-1.4	V
Diode Continuous Forward Current	I _S		-	-	-50	A
Reverse Recovery Time	t _{rr}	I _F =-20A,	-	47	-	ns
Reverse Recovery Charge	Q _{rr}	dI/dt=-100A/us	-	58	-	nC
Dynamic Characteristics²						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	4.8	-	Ω
Input capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =-30V f=1.0MHz	-	6217	-	pF
Output capacitance	C _{OSS}		-	159	-	
Reverse transfer capacitance	C _{RSS}		-	2	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =-10V, V _{DS} =-30V, R _L =1.5Ω, R _G =3Ω	-	15	-	ns
Turn-on Rise time	t _r		-	17	-	
Turn-off delay time	t _{D(OFF)}		-	37	-	
Turn-off Fall time	t _f		-	44	-	
Total gate charge	Q _g	V _{GS} =-10V, I _D =-20A V _{DS} =-20V	-	61.8	-	nC
Gate-source charge	Q _{gs}		-	55.3	-	
Gate-drain charge	Q _{gd}		-	7.7	-	

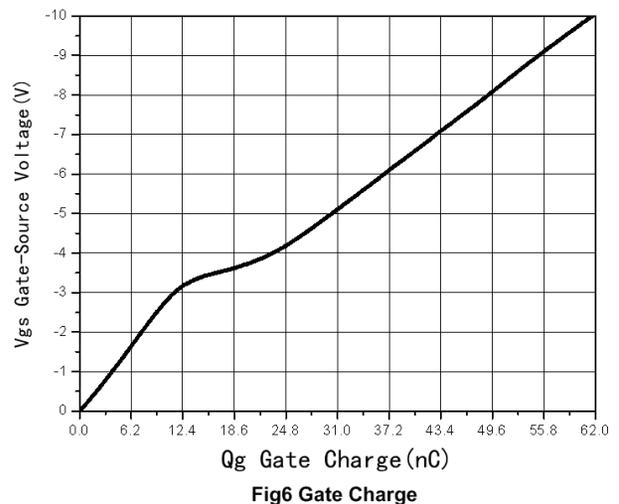
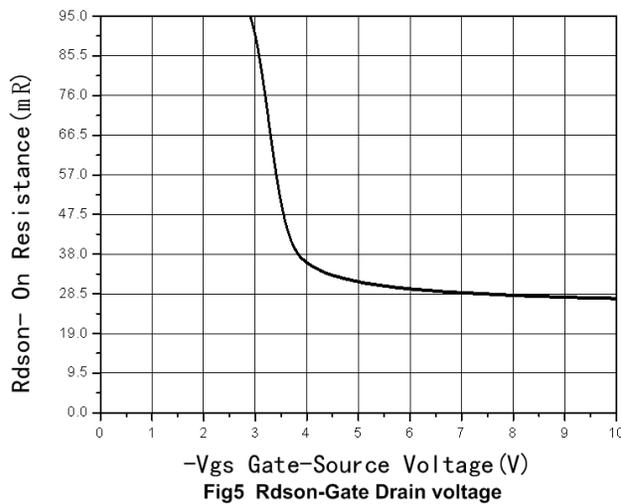
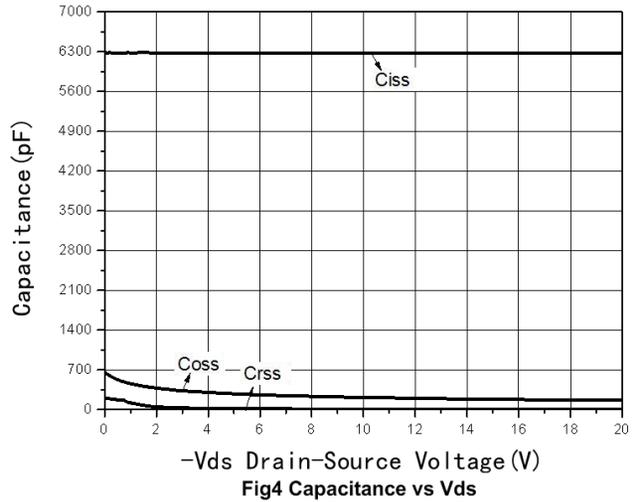
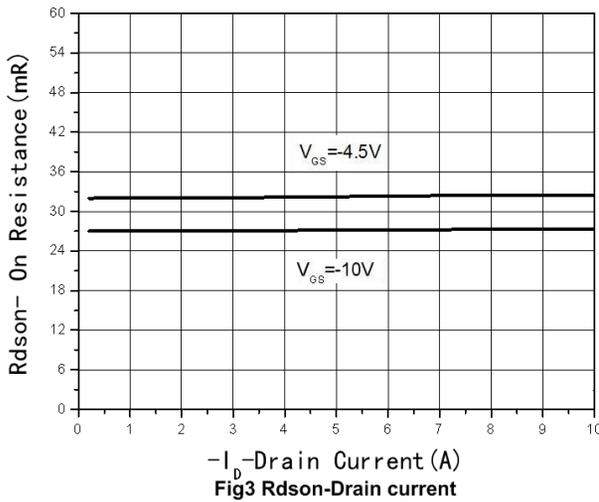
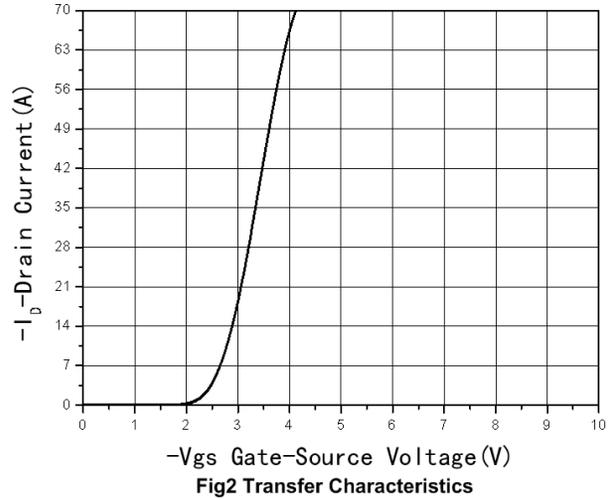
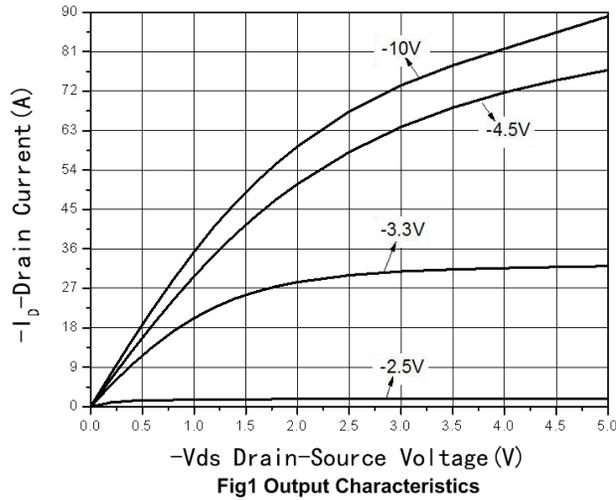
Note: 1: Pulse test; pulse width ≤ 300ns, duty cycle ≤ 2%.

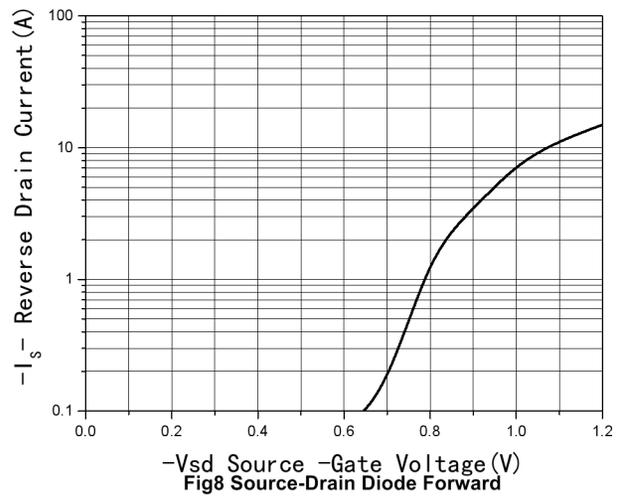
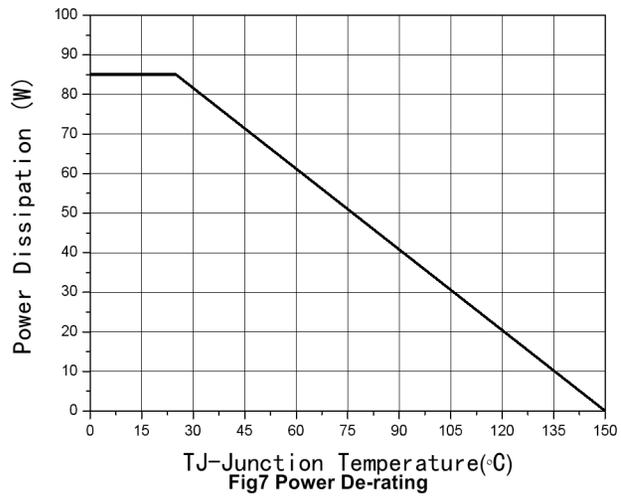
2: Guaranteed by design, not subject to production testing.

Thermal Characteristics

Parameter	Symbol	Typical	Unit
Thermal Resistance-Junction to Case	R _{θJC}	1.7	°C/W
Thermal Resistance junction-to ambient	R _{θJA}	62.5	

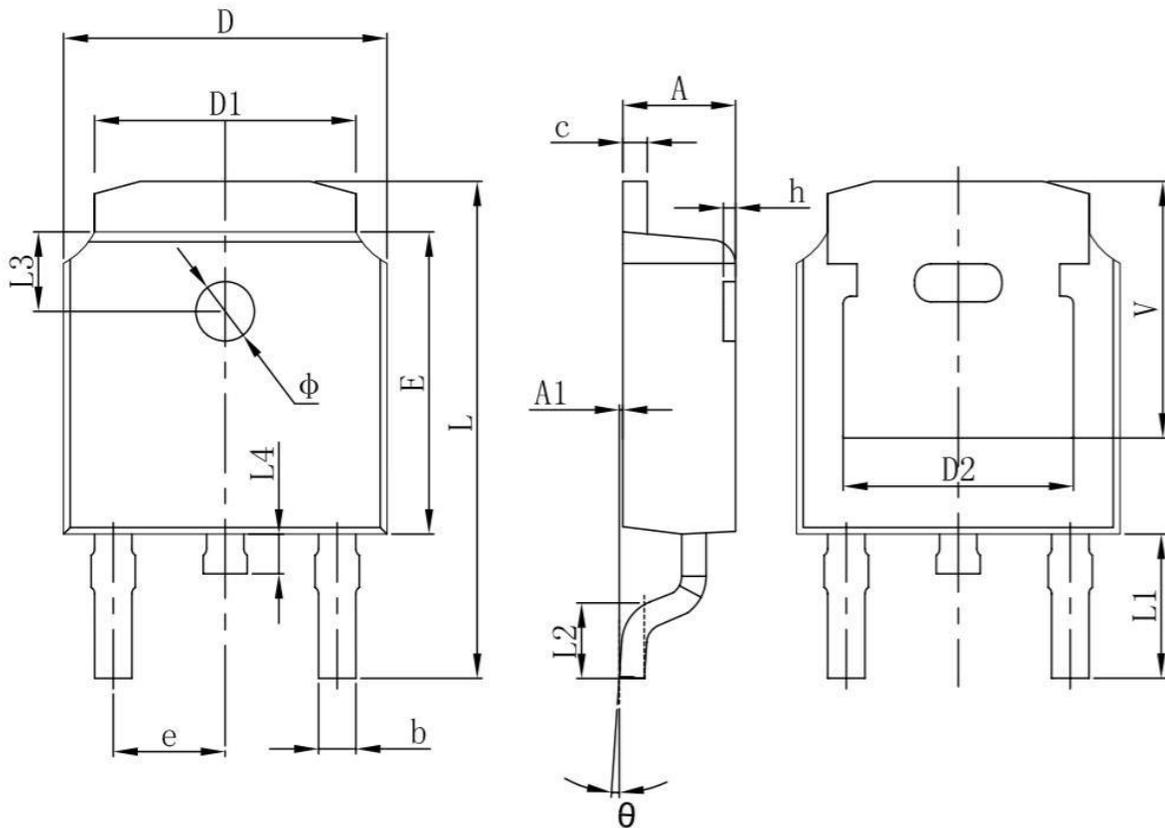
Typical Performance Characteristics





Package Information

- TO-252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	